



# INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

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Application Number

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Applicant(s)

Tai Chung CHAI

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\*EXAMINER  
INITIAL

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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2

Nakazawa, Tsutomu et al., A Novel Structure to Realize Crack-Free Plastic Packages During Reflow Soldering Process-Development of Chip Side Support (CSS) Package, IEEE Transactions on Components Packaging and Manufacturing Technology - Part C, Vol. 19, No. 1, January 1996, pp. 61-69.

1

1

Chan, K. C. and Chai, T. C., Type II Popcorn Failure Analysis in Plastic Encapsulated IC Package Using Scanning Acoustic Microscopy and Cross-Sectioning (not yet published)

1

1

CHA, Ki-Bon et al.; Ultra-Thin and Crack-Free Bottom Leaded Plastic (BLP) Package Design; LG Semicon (Gold Star) Package R&D Center, Cheongju, Korea 360-480 0569-5503/95/0000 © 1995 IEEE

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DATE CONSIDERED

1-11-01

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